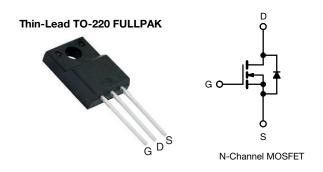
Vishay Siliconix

COMPLIANT

HALOGEN

FREE

E Series Power MOSFET



PRODUCT SUMMAR	Y	
V _{DS} (V) at T _J max.	65	50
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.208
Q _g max. (nC)	2	3
Q _{gs} (nC)	4	1
Q _{gd} (nC)	6	3
Configuration	Sin	gle

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free and halogen-free	SiHA240N60E-GE3

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	600	V
Gate-source voltage		V_{GS}	± 30	\ \ \	
Continuous drain current (T _J = 150 °C) ^e	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I-	12	
Continuous drain current (1) = 150 C)	V _{GS} at 10 V	T _C = 100 °C	I _D	7	Α
Pulsed drain current ^a			I _{DM}	30	
Linear derating factor			0.63	W/°C	
Single pulse avalanche energy b			E _{AS}	81	mJ
Maximum power dissipation		P _D	31	W	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$		dv/dt	100	\//no	
Reverse diode dv/dt ^d			dv/di	28	- V/ns
Soldering recommendations (peak temperature	ering recommendations (peak temperature) c For 10 s 260		°C		
Mounting torque, M3 screw			0.6	Nm	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 2.4 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting T_J = 25 °C
- e. Limited by maximum junction temperature



Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R_{thJA}	-	65	°C/W
Maximum junction-to-case (drain)	R_{thJC}	-	4.0	C/ VV

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static				L			
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.63	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	3.0	-	5.0	V
Cata acuraa laakaga	1	,	V _{GS} = ± 20 V	-	-	± 100	nA
Gate-source leakage	I_{GSS}	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zero gate voltage drain current	l	V _{DS} =	= 600 V, V _{GS} = 0 V	-	-	1	μA
zero gate voltage drain current	I _{DSS}	$V_{DS} = 480 \text{ V}$	', V _{GS} = 0 V, T _J = 125 °C	-	-	10	μΑ
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 5.5 A	-	0.208	0.240	Ω
Forward transconductance ^a	9 _{fs}	V _{DS} :	= 20 V, I _D = 5.5 A	-	4	-	S
Dynamic							
Input capacitance	C_{iss}		$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ $f = 1 \text{ MHz}$		783	-	
Output capacitance	C _{oss}	,			50	-	
Reverse transfer capacitance	C_{rss}				5	-	_
Effective output capacitance, energy related ^a	$C_{o(er)}$	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	32	-	pF
Effective output capacitance, time related ^b	$C_{o(tr)}$			-	187	-	
Total gate charge	Qg			-	15	23	
Gate-source charge	Q_{gs}	$V_{GS} = 10 \text{ V}$	$I_D = 5.5 \text{ A}, V_{DS} = 480 \text{ V}$	-	4	-	nC
Gate-drain charge	Q_{gd}			-	6	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 480 V, I _D = 5.5 A,		-	15	30	
Rise time	t _r			-	14	28	ns
Turn-off delay time	t _{d(off)}	V _{GS} =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		26	52	
Fall time	t _f]		-	14	28	
Gate input resistance	R_g	f = 1 MHz, open drain		0.8	1.5	3.0	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	12	
Pulsed diode forward current	I _{SM}			-	-	30	- A
Diode forward voltage	V _{SD}	T _J = 25 °C	C, I _S = 5.5 A, V _{GS} = 0 V	-	-	1.2	V
Reverse recovery time	t _{rr}			-	209	418	ns
Reverse recovery charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}$, $I_F = I_S = 5.5 \text{A}$, $di/dt = 100 \text{A/}\mu\text{s}$, $V_R = 25 \text{V}$		-	2.1	4.2	μC
Reverse recovery current	I _{RRM}			-	18	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

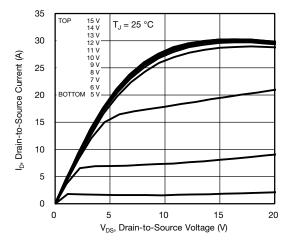


Fig. 1 - Typical Output Characteristics

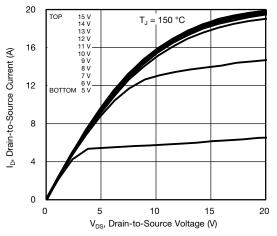


Fig. 2 - Typical Output Characteristics

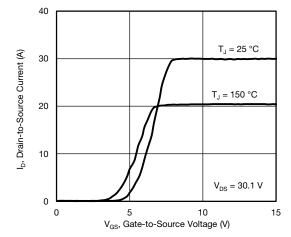


Fig. 3 - Typical Transfer Characteristics

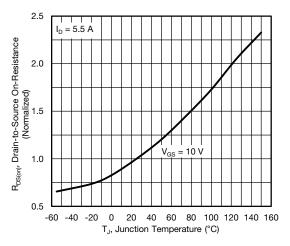


Fig. 4 - Normalized On-Resistance vs. Temperature

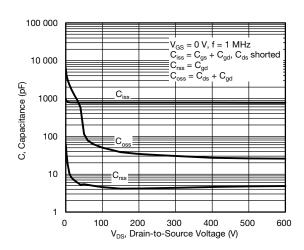


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

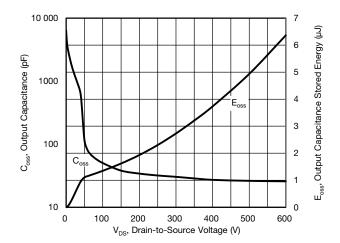


Fig. 6 - Coss and Eoss vs. VDS



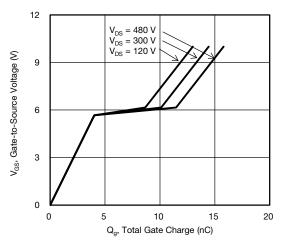


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

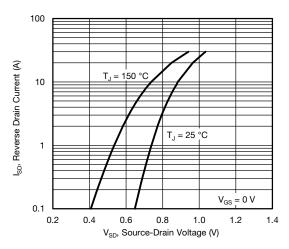


Fig. 8 - Typical Source-Drain Diode Forward Voltage

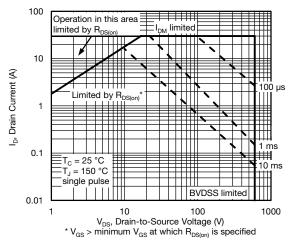


Fig. 9 - Maximum Safe Operating Area

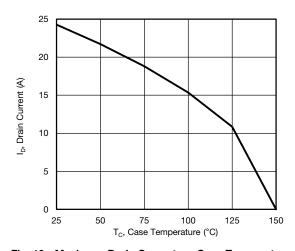


Fig. 10 - Maximum Drain Current vs. Case Temperature

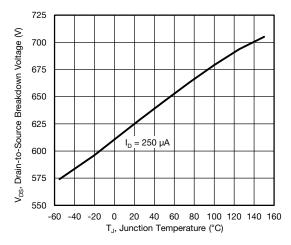


Fig. 11 - Temperature vs. Drain-to-Source Voltage



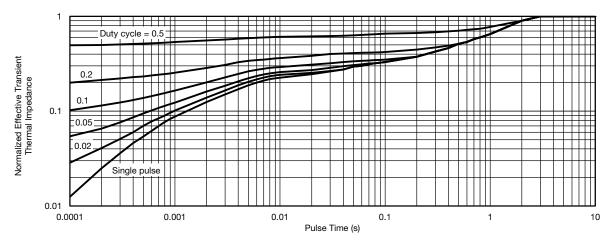


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

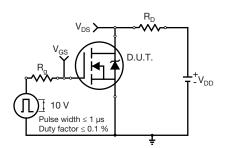


Fig. 13 - Switching Time Test Circuit

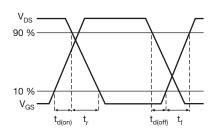


Fig. 14 - Switching Time Waveforms

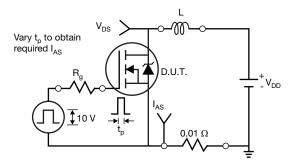


Fig. 15 - Unclamped Inductive Test Circuit

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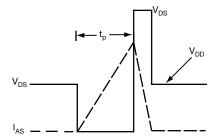


Fig. 16 - Unclamped Inductive Waveforms

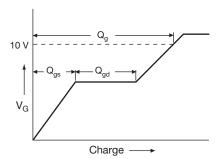


Fig. 17 - Basic Gate Charge Waveform

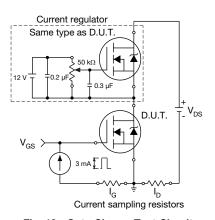


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit

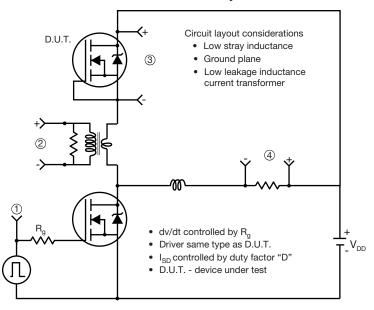


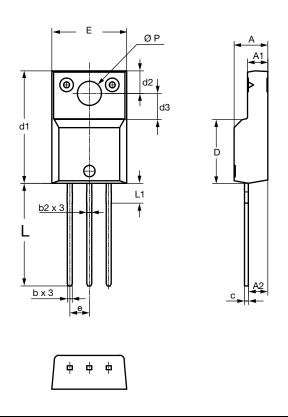


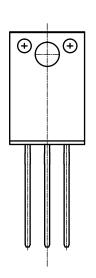
Fig. 19 - For N-Channel

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TO-220 FULLPAK Thin Lead





	DIMENSIONS				
SYMBOL	MILLIN	IETERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
А	4.30	4.70	0.169	0.185	
A1	2.50	2.90	0.098	0.114	
A2	2.40	2.80	0.094	0.110	
b	0.60	0.80	0.024	0.031	
b2	0.60	0.90	0.024	0.035	
С	-	0.60	-	0.024	
D	8.30	8.70	0.327	0.342	
d1	14.70	15.30	0.579	0.602	
d2	2.90	3.10	0.114	0.122	
d3	3.30	3.70	0.130	0.146	
Е	9.70	10.30	0.382	0.406	
е	2.50	2.70	0.098	0.106	
L	13.40	13.80	0.528	0.543	
L1	1.00	2.80	0.039	0.110	
ØP	3.00	3.40	0.118	0.134	

ECN: E20-0684-Rev. D, 28-Dec-2020

DWG: 6021



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Vishay

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